

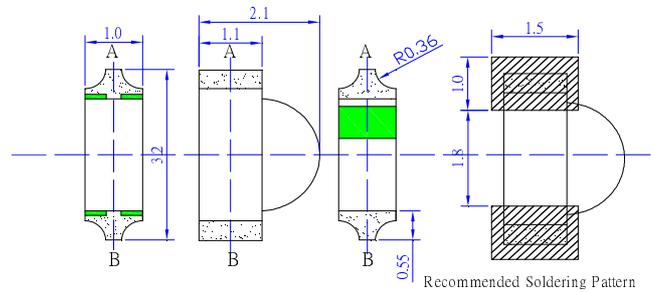
■Features

- Single chip
- Compact package outline
(L x W x T) of 3.2mm x 1.0mm x2.1mm
- Compatible to IR reflow soldering.
- Water Clear Lens Type

■Applications

- Automatic Control System
- Photo Detector
- Computer I/O Peripheral

■Outline Dimension



A ← ● → B
A:Cathode
B:Anode

Unit:mm
Tolerance:±0.20mm
unless otherwise noted

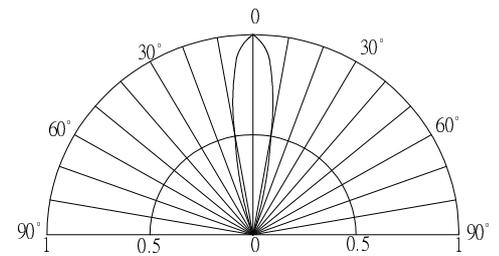
■Absolute Maximum Rating

(Ta=25°C)

Item	Symbol	Value	Unit
DC Forward Current	I _F	100	mA
Pulse Forward Current*	I _{FP}	300	mA
Reverse Voltage	V _R	5	V
Power Dissipation	P _D	130	mW
Operating Temperature	Topr	-30 ~ +85	°C
Storage Temperature	Tstg	-40~ +100	°C
Lead Soldering Temperature	Tsol	260°C/5sec	-

*Pulse width Max 0.1ms, Duty ratio max 1/10

■Directivity



■Electrical -Optical Characteristics

(Ta=25°C)

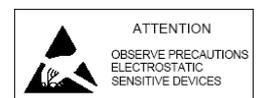
Item	Symbol	Condition	Min.	Typ.	Max.	Unit
DC Forward Voltage	V _F	I _F =5mA	-	1.2	1.3	V
DC Reverse Current	I _R	V _R =5V	-	-	10	μA
Peak Wavelength	λ _p	I _F =5mA	-	940	-	nm
Transmit Bandwidth	λ	I _F =5mA	35	45	55	nm
Radiant Intensity	I _e	I _F =5mA	1	5	-	mW/Sr
50% Power Angle	2θ _{1/2}	I _F =5mA	-	20	-	deg

*1 Tolerance of measurements of Peak wavelength is ±1nm

*2 Tolerance of measurements of radiant intensity is ±15%

*3 Tolerance of measurements of forward voltage is ±0.1V

LED & Application Technologies



■ Typical Electrical/Optical/Characteristics Curves

Fig.1 Forward Current vs Ambient Temperature

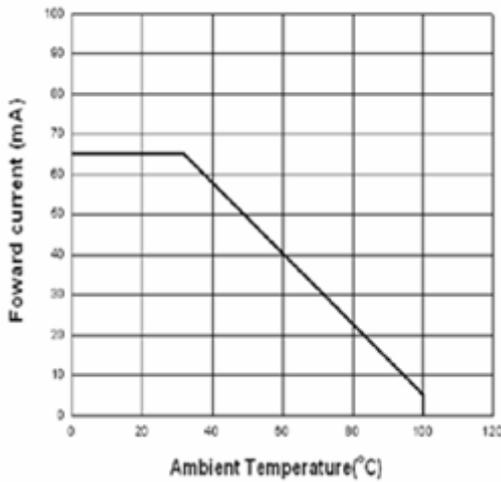


Fig.2 Spectral Sensitivity

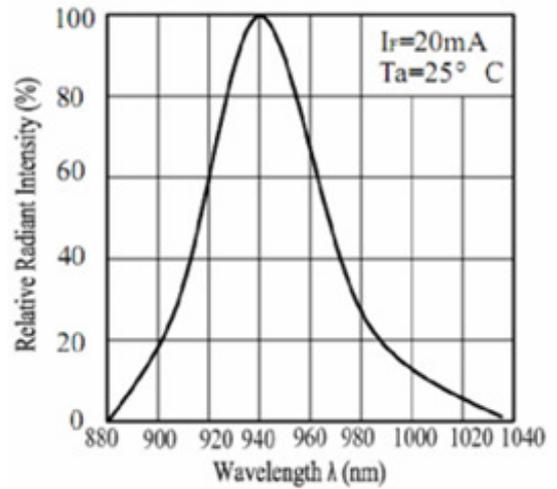


Fig.3 Relative Intensity vs. Forward Current

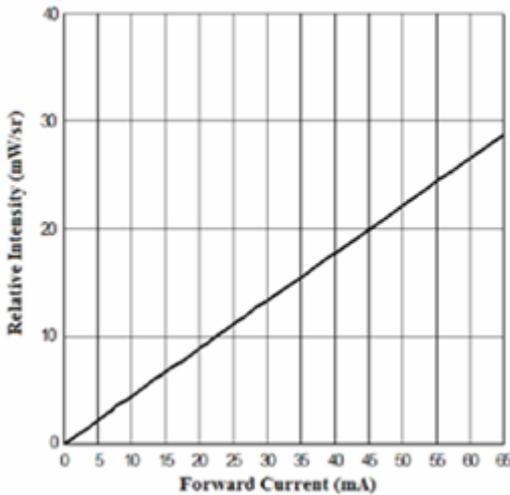


Fig.4 Forward Current vs. Forward Voltage

